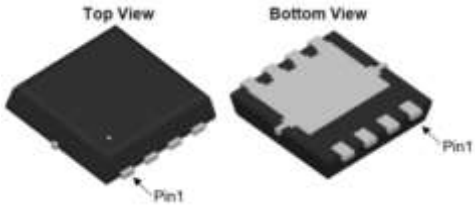
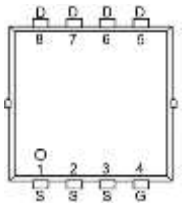
30V_{DS}/±20V_{GS} N-Channel Enhancement Mode MOSFET

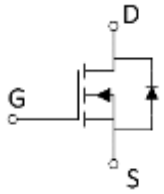
Features

- V_{DS}=30V,I_D=35A
- $R_{DS(ON)}$=12mΩ（TYP.）V_{GS}=10V
- $R_{DS(ON)}$=18mΩ（TYP.）V_{GS}=4.5V
- Reliable and Rugged
- Avalanche Rated
- Low On-Resistance
- High Current Capability

PDFN3333







Applications

- Load Switch
- Power management in portable/desktop PCs
- DC/DC conversion

Ordering Information

Device	package	Device Marking	Package Qty.
AGM310AP1	**PDFN3333**	**	**5000/PCS**

Absolute Maximum Ratings (T$_C$=25℃,unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V_{GS}=0V)	V_{DS}	30	V
Gate-Source Voltage (V_{GS}=0V,static)	V_{GS}	±20	V
Continuous Drain Current (T_C=25℃)	I_D	35	A
Continuous Drain Current (T_C=100℃)		18	A
Pulesd Drain Current	I_{DM}	180	A
Single Pulsed Avalanche Energy	E_{AS}	22	mJ
Maximum Power Dissipation (T_C =25℃)	P_D	20	W
Operating,Storage Temperature Range	T_J,T_{STG}	-55~150	℃

Electrical Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V,I_D=250μA	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V, V_{GS}=0V	-	-	1	μA
Gate -Source Leakage Current	I_{GSS}	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}= V_{GS},I_D=250μA	1	1.8	3	V
Drain-Source On-stage Resistance	$R_{DS(ON)}$	V_{GS}=10V,I_D=20A	-	-	12	mΩ
		V_{GS}=4.5V,I_D=20A	-	-	20	

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance,Junction-to-Case	$R_{\theta JC}$	-	6	-	℃/ W
Thermal Resistance,Junction-to-Ambient	$R_{\theta JA}$	-	75	-	℃/ W

Dynamic Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	V_{DS}=15V	-	572	-	pF
Output capacitance	C_{oss}	V_{GS}=0V	-	81	-	
Reverse transfer capacitance	C_{rss}	f=1MHz	-	65	-	
Gate Resistance	R_g	f=1MHz	-	1.5	-	Ω
Total Gate Charge	Q_g	V_{DS}=15V	-	15.9	-	nC
Gate Source Charge	Q_{gs}	V_{GS}=10V	-	2.9	-	
Gate Drain Charge	Q_{gd}	I_D=20A	-	3.3	-	
Turn-on delay Time	$t_{d(on)}$	V_{GS}=10V	-	6.3	-	ns
Rise time	t_r	V_{DS}=15V	-	2.7	-	
Turn-off delay Time	$t_{d(off)}$	R_L=0.75Ω	-	18.6	-	
Fall time	t_f	R_G=3Ω	-	4.2	-	

Reverse Diode Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Body Diode Forward Voltage	V_{SD}	V_{GS}=0V,I_{SD}=1A	-		1.2	V
Reverse Recovery Time	t_{rr}	V_{GS}=0V,I_{SD}=20A	-	32	50	ns
Reverse Recovery Charge	Q_{rr}	d_i/d_t=500A/μs	-	13.5	20	nC

Electrical Characteristics Diagrames

Figure 1. On-Regin Characteristics

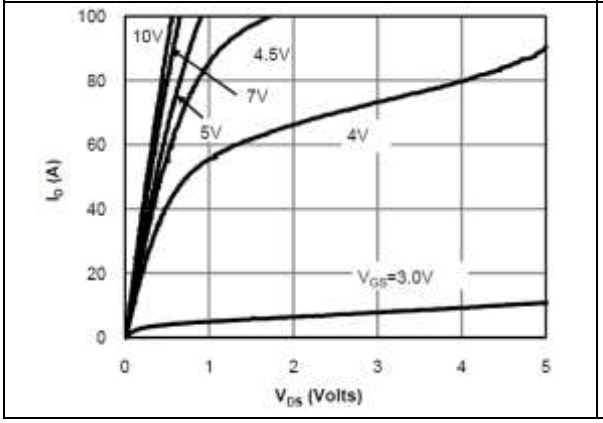


Figure 2. Transfer Characteristics

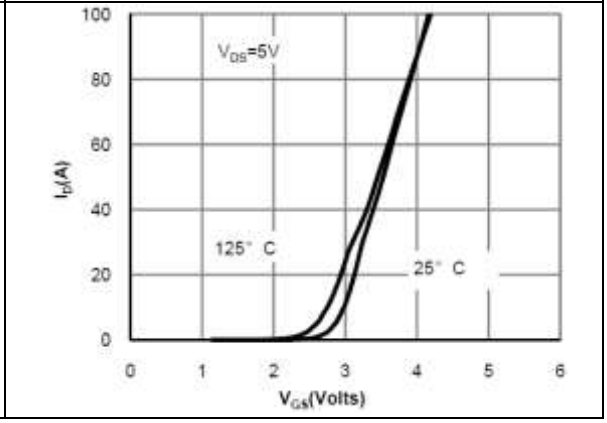


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

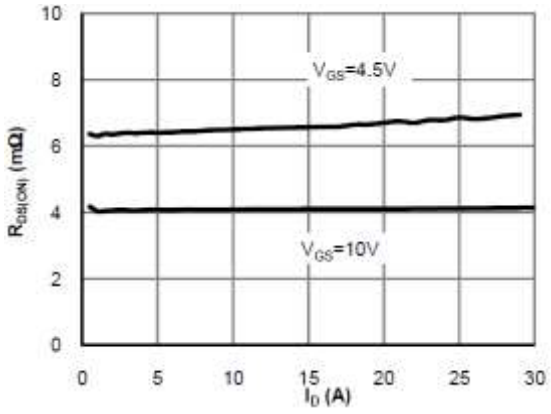


Figure 4. On-Resistance vs. Junction Temperature

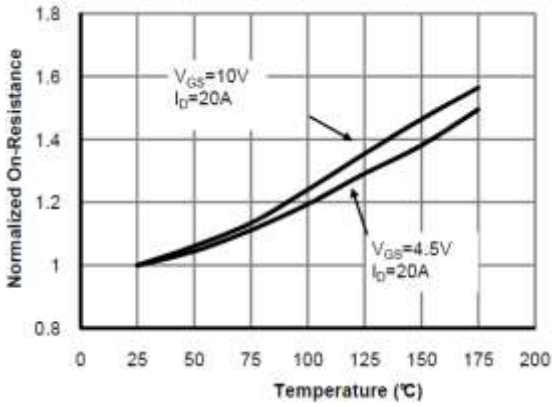


Figure 5. On-Resistance vs. Gate-Source Voltage

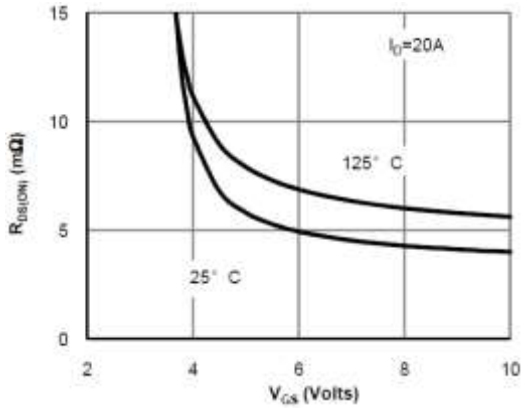


Figure 6. Body-Diode Characteristics

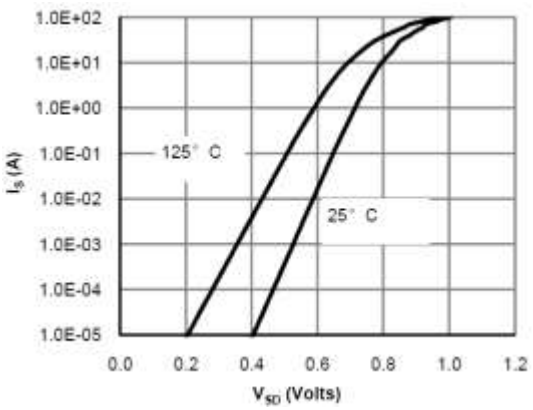


Figure 7. Gate-Charge Characteristics

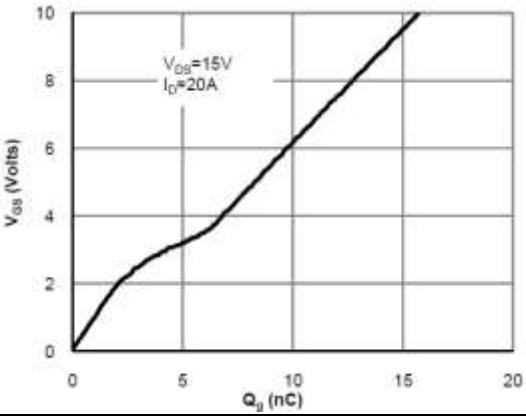


Figure 8. Capacitance Characteristics